

**Features**

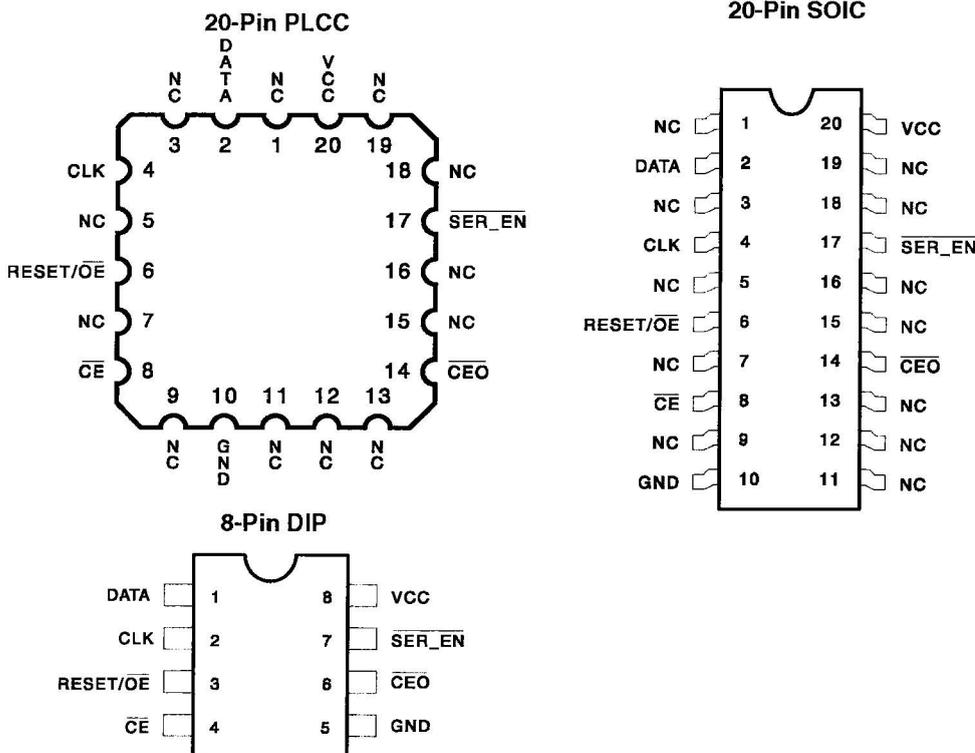
- E<sup>2</sup> Programmable 65,536 x 1, 131,072 x 1, and 262,144 x 1 bit Serial Memories Designed To Store Configuration Programs For Programmable Gate Arrays
- Simple Interface to SRAM FPGAs Requires Only One User I/O Pin
- Compatible With AT6000 FPGAs, ATT3000 FPGA, EPF8000 FPGAs, ORCA FPGAs, XC2000, XC3000, XC4000, XC5000 FPGAs
- Cascadable To Support Additional Configurations or Future Higher-density Arrays (17C128 and 17C256 only)
- Low-power CMOS EEPROM Process
- Programmable Reset Polarity
- Available In the Space-efficient Plastic DIP or Surface-mount PLCC and SOIC Packages
- In-system Programmable Via 2-Wire Bus
- Emulation of 24CXX Serial E<sup>2</sup>PROMs

**Description**

The AT17C65/128/256 (AT17CXXX family) FPGA Configuration E<sup>2</sup>PROMS (Configurator) provide an easy-to-use, cost-effective configuration memory for Field Programmable Gate Arrays. Both the AT17C65 and the AT17C128 are packaged in the 8-pin DIP and the popular 20-pin Plastic Leaded Chip Carrier, and SOIC. The AT17C256 is available in 14-pin SOIC or 20-pin PLCC or SOIC packages. The AT17CXXX family uses a simple serial-access procedure to configure one or more FPGA devices. The AT17CXXX organization supplies enough memory to configure one or multiple smaller FPGAs. Using a special feature of the AT17CXXX, the user can select the polarity of the reset function by programming a special E<sup>2</sup>PROM bit.

The AT17C65/128/256 can be programmed with the standard programmers from other manufacturers.

**Pin Configurations**



**FPGA  
Configuration  
E<sup>2</sup>PROM**

65K, 128K, and 256K



## Controlling The AT17C65/128/256 Serial E<sup>2</sup>PROMs

Most connections between the FPGA device and the Serial E<sup>2</sup>PROM are simple and self-explanatory:

- The DATA output of the AT17C65/128/256 drives DIN of the FPGA devices.
- The master FPGA CCLK output drives the CLK input of the AT17C65/128/256.
- The  $\overline{\text{CEO}}$  output of any AT17C128/256 drives the  $\overline{\text{CE}}$  input of the next AT17C128/256 in a cascade chain of PROMs.
- $\overline{\text{SER\_EN}}$  must be connected to  $V_{\text{CC}}$ .

There are, however, two different ways to use the inputs  $\overline{\text{CE}}$  and  $\overline{\text{OE}}$ , as shown in the AC Characteristics Waveform.

### Condition 1

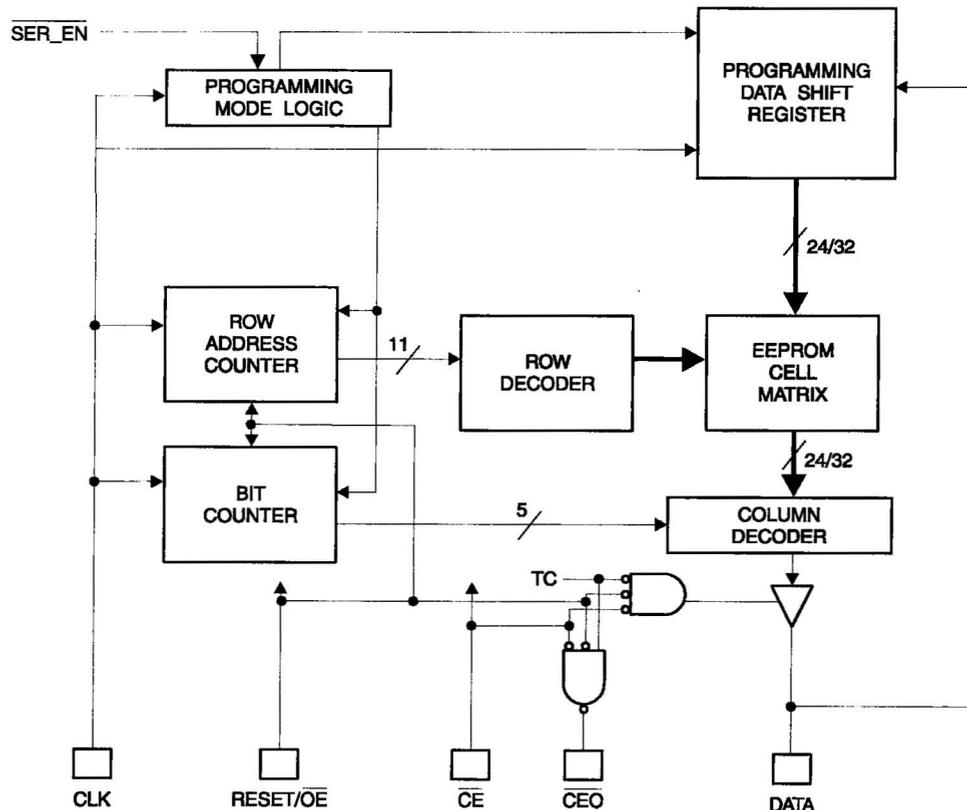
The simplest connection is to have the FPGA D/P output drive both  $\overline{\text{CE}}$  and  $\overline{\text{RESET/OE}}$  in parallel. Due to its simplicity, however, this method will fail if the FPGA receives an external reset condition during the configuration cycle.

If a system reset is applied to the FPGA, it will abort the original configuration and then reset itself for a new configuration, as intended. Of course, the AT17C65/128/256 does not see the external reset signal and will not reset its internal address counters and, consequently, will remain out of sync with the FPGA for the remainder of the configuration cycle.

### Condition 2

The FPGA D/P output drives only the CE input of the AT17C65/128/256, while its  $\overline{\text{OE}}$  input is driven by the inversion of the FPGA RESET input. This connection works under all normal circumstances, even when the user aborts a configuration before D/P has gone High. A high level on the RESET/ $\overline{\text{OE}}$  input to the AT17CXXX during FPGA reset clears the PROM internal address pointer, so that the reconfiguration starts at the beginning. The AT17C65/128/256 does not require an inverter since the RESET polarity is programmable.

## Block Diagram



## Pin Configurations

PLCC/SOIC		DIP		
Pin	Pin	Name	I/O	Description
2	1	DATA	I/O	Three-state DATA output for reading. Input/Output pin for programming.
4	2	CLK	I	Clock input. Used to increment the internal address and bit counter for reading and programming.
6	3	RESET/OE	I	RESET/Output Enable input. A Low level on both the $\overline{CE}$ and $\overline{RESET/OE}$ inputs enables the data output driver. A High level on RESET/OE resets both the address and bit counters. The logic polarity of this input is programmable as either $\overline{RESET/OE}$ or RESET/OE. This document describes the pin as RESET/OE.
8	4	$\overline{CE}$	I	Chip Enable input. Used for device selection. A Low level on both $\overline{CE}$ and $\overline{OE}$ enables the data output driver. A High level on CE disables both the address and bit counters and forces the device into a low power mode.
10	5	GND		Ground pin.
14	6	$\overline{CEO}$	O	Chip Enable Out output. This signal is asserted Low on the clock cycle following the last bit read from the memory. It will stay Low as long as $\overline{CE}$ and $\overline{OE}$ are both Low. It will then follow CE until OE goes High. Thereafter CEO will stay High until the entire PROM is read again and senses the status of RESET polarity.
17	7	$\overline{SER\_EN}$	I	Serial enable is normally high during FPGA loading operations. Bringing SER_EN low, enables the two wire serial interface mode for programming.
20	8	Vcc		+5V power supply input.

## FPGA Master Serial Mode Summary

The I/O and logic functions of the FPGA and their associated interconnections are established by a configuration program. The program is loaded either automatically upon power up, or on command, depending on the state of the three FPGA mode pins. In Master Mode, the Logic Cell

Array automatically loads the configuration program from an external memory. The Serial Configuration E<sup>2</sup>PROM has been designed for compatibility with the Master Serial Mode.

## Absolute Maximum Ratings\*

Operating Temperature.....	-55°C to +125°C
Storage Temperature.....	-65°C to +150°C
Voltage on Any Pin with Respect to Ground .....	-0.1V to V <sub>CC</sub> + 0.5V
Supply Voltage (V <sub>CC</sub> ).....	-0.5V to +7.0V
Maximum Soldering Temp. (10 s @ 1/16 in.) ..	260°C
ESD (R <sub>ZAP</sub> = 1.5K, C <sub>ZAP</sub> = 100 pF).....	2000V

\*NOTICE: Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those listed under Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time may affect device reliability.

## Cascading Serial Configuration E<sup>2</sup>PROMs (AT17C128 and AT17C256)

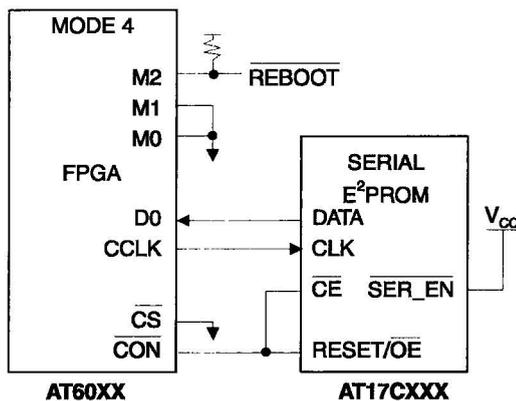
For multiple FPGAs configured as a daisy-chain, or for future FPGAs requiring larger configuration memories, cascaded Configurators provide additional memory (17C128 and 17C256 only).

After the last bit from the first Configurator is read, the next clock signal to the Configurator asserts its  $\overline{CE}$  output Low and disables its DATA line. The second Configurator recognizes the Low level on its  $\overline{CE}$  input and enables its DATA output.

After configuration is complete, the address counters of all cascaded Configurators are reset if  $\overline{RESET}$  goes Low forcing the  $\overline{RESET/OE}$  on each Configurator to go High.

If the address counters are not to be reset upon completion, then the  $\overline{RESET/OE}$  inputs can be tied to ground.

### Mode 4 Configuration



### Programming Mode

The programming mode is entered by bringing  $\overline{SER\_EN}$  low. In this mode the chip can be programmed by a 2-wire interface. The programming is done at  $V_{CC}$  supply only. Programming (High) voltages are generated inside the chip. See the Programming Specification for Atmel's Configuration Memories Application Note for further information.

### AT17CXXX Reset Polarity

The AT17CXXX lets the user choose the reset polarity as either  $\overline{RESET/OE}$  or  $\overline{RESET/OE}$ .

### Standby Mode

The AT17CXXX enters a low-power standby mode whenever  $\overline{CE}$  is asserted High. In this mode, the Configurator consumes less than 1.0 mA of current. The output remains in a high impedance state regardless of the state of the OE input.

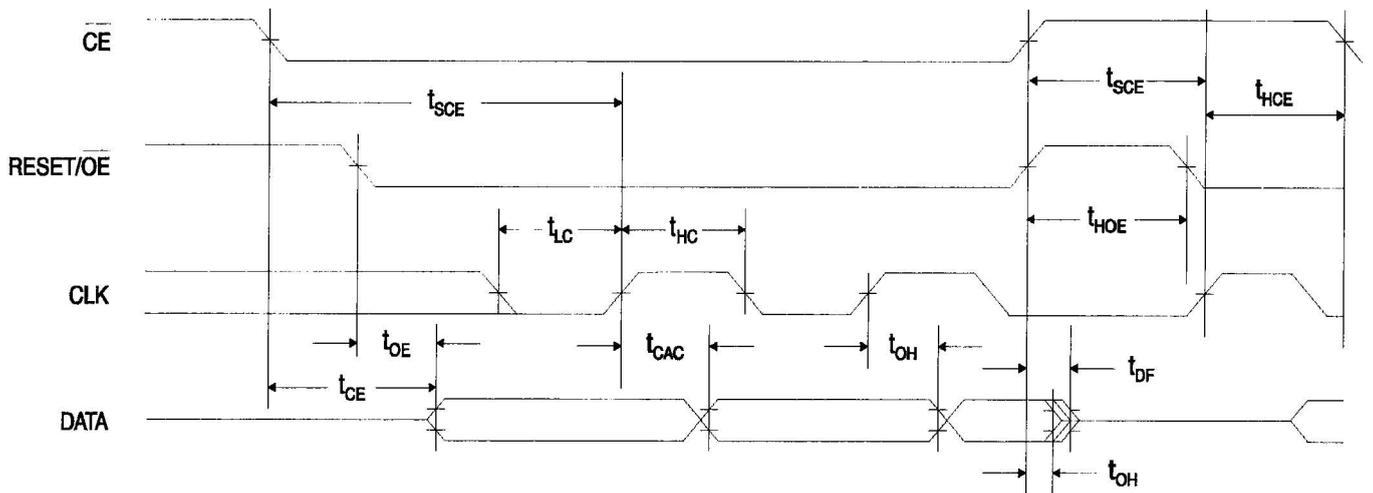
### Operating Conditions

Symbol	Description	Min	Max	Units
$V_{CC}$	Commercial	Supply voltage relative to GND -0°C to +70°C		V
	Industrial	Supply voltage relative to GND -40°C to +85°C		V
	Military . . . . .	Supply voltage relative to GND -55°C to +125°C		V

DC Characteristics Over Operating Conditions

Symbol	Description		Min	Max	Units
V <sub>IH</sub>	High-level input voltage		2.0	V <sub>CC</sub>	V
V <sub>IL</sub>	Low-level input voltage		0	0.8	V
V <sub>OH</sub>	High-level output voltage (I <sub>OH</sub> = -4 mA)	Commercial	3.86		V
V <sub>OL</sub>	Low-level output voltage (I <sub>OL</sub> = +4 mA)			0.32	V
V <sub>OH</sub>	High-level output voltage (I <sub>OH</sub> = -4 mA)	Industrial	3.76		V
V <sub>OL</sub>	Low-level output voltage (I <sub>OL</sub> = +4 mA)			0.37	V
V <sub>OH</sub>	High-level output voltage (I <sub>OH</sub> = -4 mA)	Military	3.7		V
V <sub>OL</sub>	Low-level output voltage (I <sub>OL</sub> = +4 mA)			0.4	V
I <sub>CCA</sub>	Supply current, active mode			10	mA
I <sub>L</sub>	Input or output leakage current (V <sub>IN</sub> = V <sub>CC</sub> or GND)		-10	10	μA
I <sub>CCS</sub>	Supply current, standby mode	Commercial		1	mA
		Industrial/Military		2	mA

AC Characteristics Over Operating Conditions





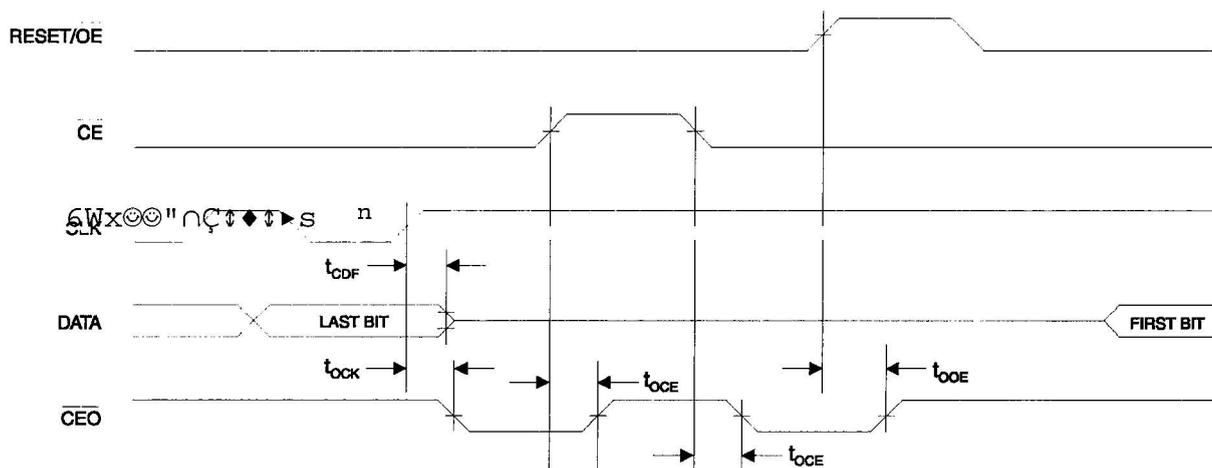
## AC Characteristics Over Operating Conditions

Symbol	Description	Commercial		Industrial/Military		Units
		Min	Max	Min	Max	
T <sub>OE</sub>	$\overline{OE}$ to Data Delay		110		150	ns
T <sub>CE</sub>	$\overline{CE}$ to Data Delay		50		50	ns
T <sub>CAC</sub>	CLK to Data Delay		50		55	ns
T <sub>OH</sub>	Data Hold From $\overline{CE}$ , $\overline{OE}$ , or CLK	0		0		ns
T <sub>DF</sub>	$\overline{CE}$ or $\overline{OE}$ to Data Float Delay		50		50	ns
T <sub>LC</sub>	CLK Low Time	30		35		ns
T <sub>HC</sub>	CLK High Time	30		35		ns
T <sub>SCE</sub>	$\overline{CE}$ Setup Time to CLK (to guarantee proper counting)	45		50		ns
T <sub>HCE</sub>	$\overline{CE}$ Hold Time to CLK (to guarantee proper counting)	0		5		ns
T <sub>HOE</sub>	$\overline{OE}$ High Time (Guarantees Counter Is Reset)	50		60		ns
F <sub>MAX</sub>	MAX Input Clock Frequency		10		10	MHz

Notes: 1. Preliminary specifications for military operating range only.  
2. AC test load = 50 pF.

3. Float delays are measured with 5 pF AC loads. Transition is measured  $\pm 500$  mV from steady state active levels.

## AC Characteristics Over Operating Conditions When Cascading



## AC Characteristics Over Operating Conditions When Cascading

Symbol	Description	Commercial		Industrial/Military		Units	
		Min	Max	Min	Max		
1	T <sub>CDF</sub>	CLK to Data Float Delay		50		50	ns
2	T <sub>OCK</sub>	CLK to $\overline{CEO}$ Delay		65		75	ns
3	T <sub>OCE</sub>	CE to $\overline{CEO}$ Delay		55		60	ns
4	T <sub>OOE</sub>	RESET/ $\overline{OE}$ to $\overline{CEO}$ Delay		55		55	ns

**Ordering Information**

Memory Size (K)	Ordering Code	Package	Operation Range
64K	AT17C65-10PC	8P3	Commercial (0°C to 70°C)
	AT17C65-10JC	20J	
	AT17C65-10SC	20S	
	AT17C65-10PI	8P3	Industrial (-40°C to 85°C)
	AT17C65-10JI	20J	
	AT17C65-10SI	20S	
128K	AT17C128-10PC	8P3	Commercial (0°C to 70°C)
	AT17C128-10JC	20J	
	AT17C128-10SC	20S	
	AT17C128-10PI	8P3	Industrial (-40°C to 85°C)
	AT17C128-10JI	20J	
	AT17C128-10SI	20S	
256K	AT17C256-10JC	20J	Commercial (0°C to 70°C)
	AT17C256-10SC	20S	
	AT17C256-10JI	20J	Industrial (-40°C to 85°C)
	AT17C256-10SI	20S	

Package Type	
<b>8P3</b>	8 Lead, 0.300" Wide, Plastic Dual Inline Package (PDIP)
<b>20J</b>	20 Lead, Plastic J-Leaded Chip Carrier (PLCC)
<b>20S</b>	20 Lead, 0.300" Wide, Plastic Gull Wing Small Outline (SOIC)

